Reinforced Isolated 3-Phase Inverter

Sensing for DC Link Voltage

Sensing for Module Temperature
Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>AMC1311 for DC_Link</td>
</tr>
<tr>
<td>002</td>
<td>AMC1301 for DC_Link</td>
</tr>
</tbody>
</table>

Assembly Note

1. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

2. THESE ASSEMBLIES MUST BE CLEAN AND FREE FROM FLUX AND ALL CONTAMINANTS. USE OF NO CLEAN FLUX IS NOT ACCEPTABLE.

3. THESE ASSEMBLIES MUST COMPLY WITH WORKMANSHIP STANDARDS IPC-A-610 CLASS 2, UNLESS OTHERWISE SPECIFIED.

4. THESE ASSEMBLIES ARE ESD SENSITIVE, ESD PRECAUTIONS SHALL BE OBSERVED.

5. THESE ASSEMBLIES ARE FOR PCB LABELS ONLY.

6. THIS ASSEMBLY NOTE IS FOR PCB LABELS ONLY.
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